

RL78/G15 Group

Renesas Flash Sample Program Type 01 SC Version (Data Flash)

Introduction

This document explains Renesas Flash Sample Program Type 01 for the RL78/G15 group in the case of using Smart Configurator(SC). It is a process which builds into a user program the functions for "the data flash memory program" included in RFSP Type 01, and it is a method for programming data flash memory using the attached sample program.

In this document, "Renesas Flash Sample Program Type 01" is described to be "RFSP Type 01" or "RFSP".

This document includes the contents in comparison with conventional RFSP Type 01 not using SC. This document distinguishes and expresses it.

Simple version : Conventional RFSP Type 01 not using SC.

SC version : RFSP Type 01 using "SC" currently explained by this document.

Target Device

The target device group by which the operation for RFSP Type 01 was confirmed.

RL78/G15 group

If this application note is applied to other microcomputers, it is necessary to modify in accordance with the specification of the microcomputer. And, be sure to evaluate enough.

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1. Specification

The sample program included in RFSP Type 01 erases the block 0 (0x9000) of a data flash area, and programs 64 bytes of data from the top of the block 0.

1.1 Operating Environment

- C Compiler Packages

Table 1-1 The Target C Compiler Packages

Package	Manufacturer	Version
CC-RL(for CS+ or e ² studio)	Renesas Electronics	V1.10 or later
IAR (Embedded Workbench)	IAR Systems	V4.21 or later

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- Emulator

Table 1-2 shows the emulator on which the operation of RFSP Type 01 was confirmed.

Table 1-2 Emulator on which RFSP Type 01 Operation was Confirmed

Emulator	Manufacturer
E2 emulator Lite	Renesas Electronics

- Target MCU

RL78/G15

1.2 Structure of Sample Program Folders

Figure 1.1 shows the structure of sample program folders.

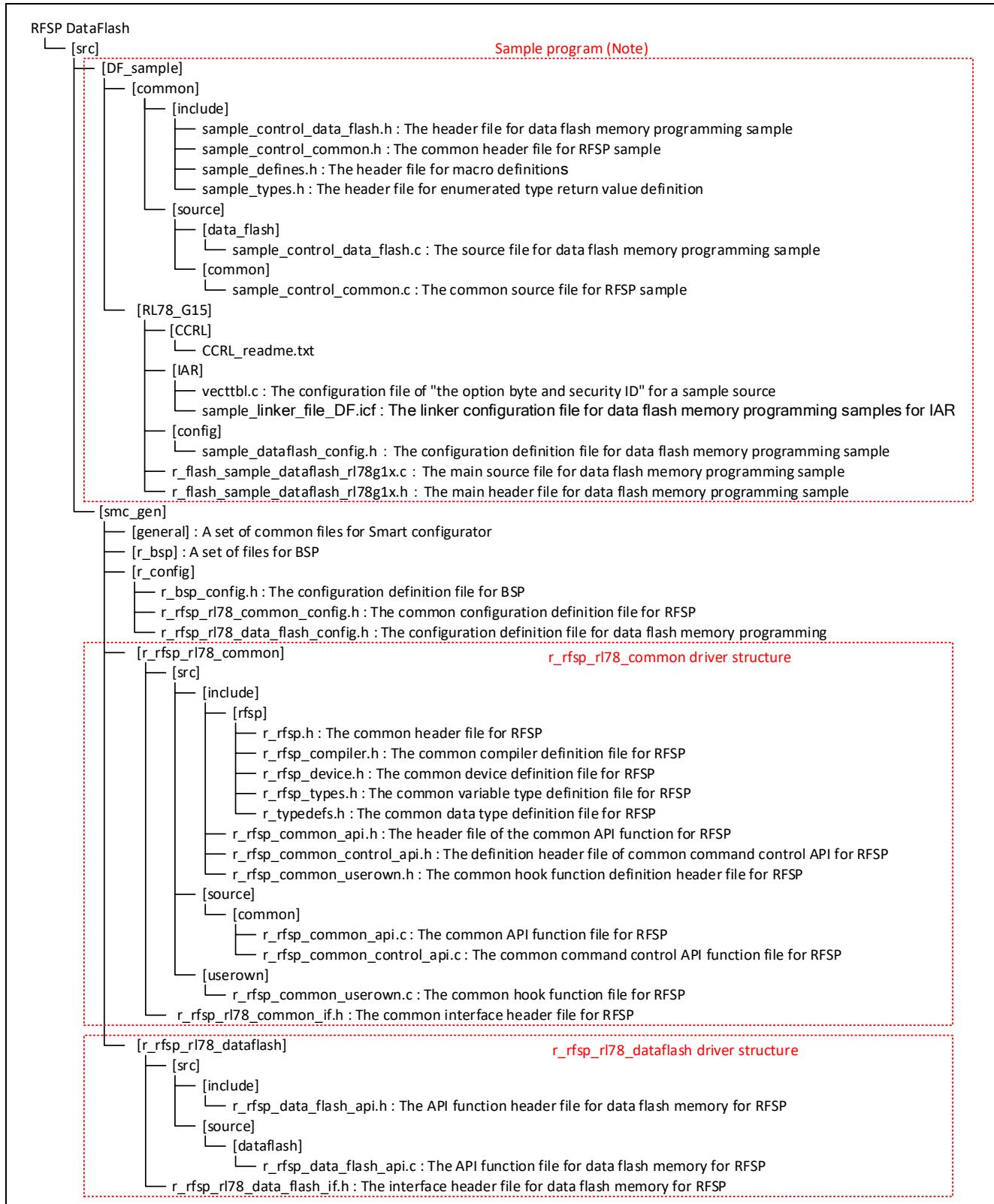


Figure 1.1 Structure of Sample Program Folders

Note: The sample program of a zip file format downloads by Smart configurator. Extract the compressed file (DF_sample.zip) outputted to the "demo" folder, and move the [DF_sample] folder under the [src] folder. Refer to "2.3 Project registration of sample program" for details of project registration.

1.3 File Structure of RFSP Program

1.3.1 File Structure of RFSP Common Program (r_rfsp_rl78_common)

The difference of SC version RFSP common program and Simple version common program is shown. Refer to the "Renesas Flash Sample Program Type01 Application Note (R20AN0652)" for the detail specification for the RFSP common program.

**Table 1-3 Difference of the Files of the SC Version RFSP and the Simple Version RFSP
(Common API : r_rfsp_rl78_common¥src¥source¥common)**

File name	Simple version	SC version
r_rfsp_common_api.c		No change
r_rfsp_common_control_api.c		No change

**Table 1-4 Difference of the File of the SC Version RFSP and the Simple Version RFSP
(Common API : r_rfsp_rl78_common¥src¥userown)**

File name	Simple version	SC version
r_rfsp_common_userown.c		No change

**Table 1-5 Difference of the Files of the SC Version RFSP and the Simple Version RFSP
(Common Header : r_rfsp_rl78_common¥src¥include)**

File name	Simple version	SC version
r_rfsp_common_api.h		No change
r_rfsp_common_control_api.h		No change
r_rfsp_common_userown.h		No change

**Table 1-6 Difference of the Files of the SC Version RFSP and the Simple Version RFSP
(Common Header : r_rfsp_rl78_common¥src¥include¥rfsp)**

File name	Simple version	SC version
r_rfsp.h		No change
r_rfsp_compiler.h		No change
r_rfsp_device.h		No change
r_rfsp_types.h		No change
r_typedefs.h		No change

**Table 1-7 Difference of the File of the SC Version RFSP and the Simple Version RFSP
(Common Interface Header : r_rfsp_rl78_common)**

File name	Simple version	SC version
r_rfsp_rl78_common_if.h	-	Newly created. Include the header file for common API.

1.3.2 File Structure for RFSP Data Flash Program (r_rfsp_rl78_dataflash)

The difference of SC version RFSP data flash program and Simple version data flash program is shown. Refer to the “Renesas Flash Sample Program Type01 Application Note (R20AN0652) ” for the detail specification for the RFSP data flash program.

**Table 1-8 Difference of the File of the SC Version RFSP and the Simple Version RFSP
(Data Flash API : r_rfsp_rl78_dataflash¥src¥source¥dataflash)**

File name	Simple version	SC version
r_rfsp_data_flash_api.c		No change

**Table 1-9 Difference of the File of the SC Version RFSP and the Simple Version RFSP
(Data Flash API Header : r_rfsp_rl78_dataflash¥src¥include)**

File name	Simple version	SC version
r_rfsp_data_flash_api.h		No change

**Table 1-10 Difference of the File of the SC Version RFSP and the Simple Version RFSP
(Data Flash Interface Header : r_rfsp_rl78_dataflash)**

File name	Simple version	SC version
r_rfsp_rl78_dataflash_if.h	-	Newly created. Include the header file for data flash API.

1.4 Data Flash Programming Processing Using a Sample Program

Figure 1.2 shows the flow chart of the sample program. The `sample_dataflash_main` function executes processing which reprograms data flash.

`Sample_DataFlashControl` function processing does not have change from Simple version. Refer to the item of "Sample_DataFlashControl function" on Renesas Flash Sample Program Type01 Application Note (R20AN0652) .

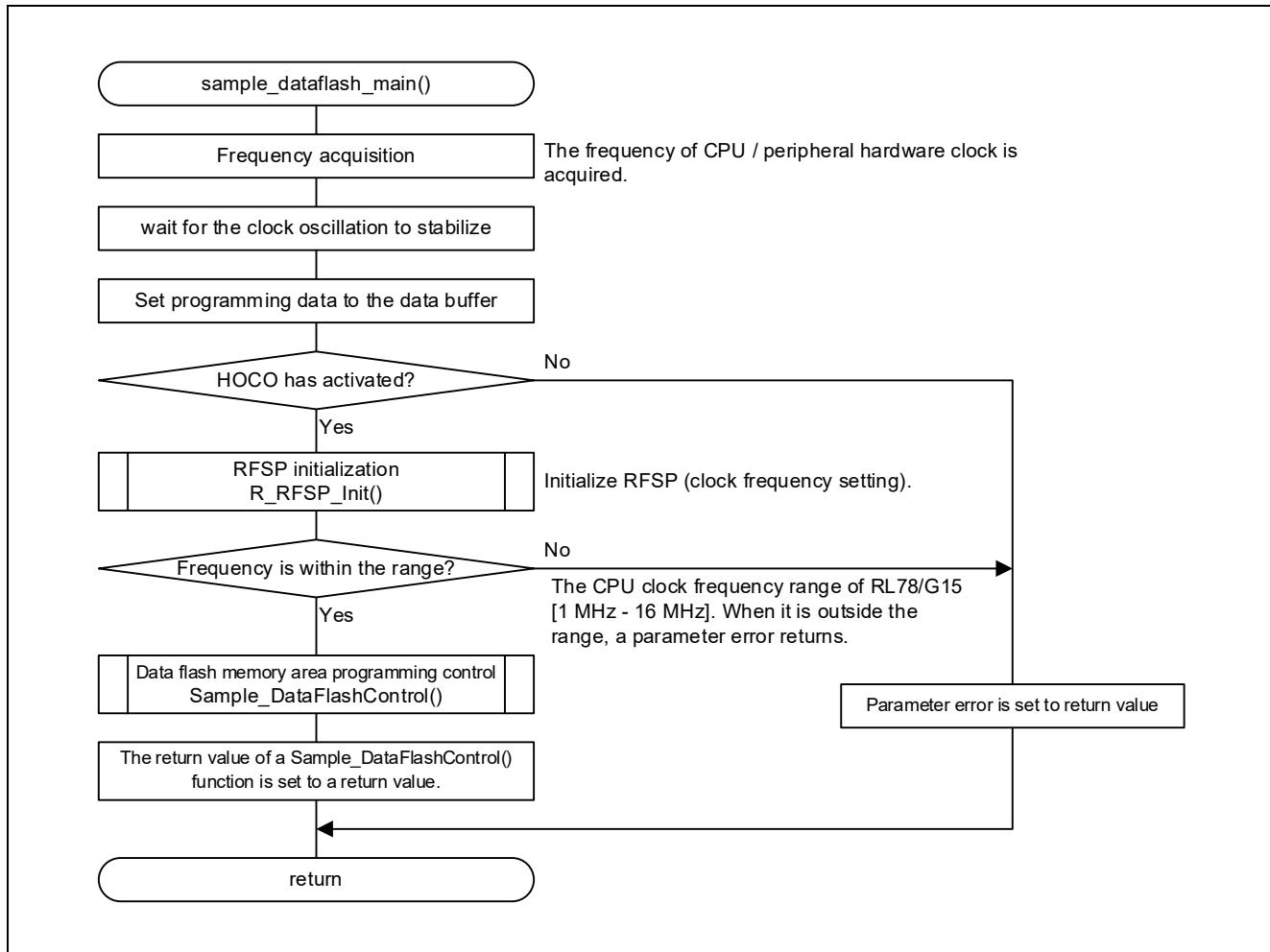


Figure 1.2 The Flow Chart of the Sample Program

Notes: 1. "Frequency acquisition" of CPU and peripheral hardware clock settings is using the function included in the "RL78 Family Board Support Package".

2. Creating a Sample Project for Data Flash Reprogramming

2.1 Example of Creating a Sample Project

2.1.1 In Case of CS+

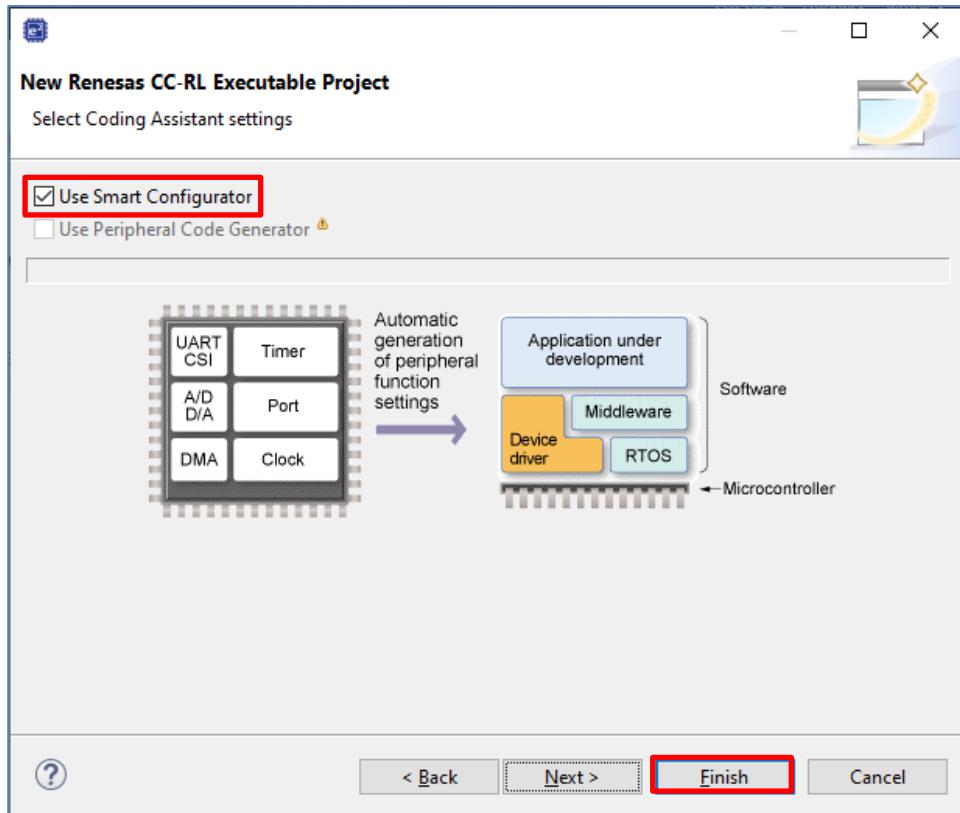
Refer to Renesas Flash Sample Program Type01 Application Note (R20AN0652) "Example of Creating a Sample Project" to create a project.

2.1.2 In Case of e²studio

Refer to Renesas Flash Sample Program Type01 Application Note (R20AN0652) "Example of Creating a Sample Project" to create a project.

In this application note, because smart Configurator is used, push a "Next" button after selecting a target device and a debugging tool. And perform the following processes.

Select "Use Smart Configurator" and push a "Finish" button.



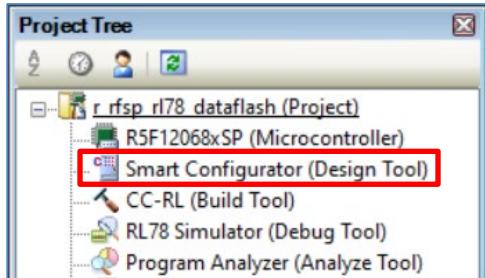
2.1.3 In Case of IAR EW for Renesas RL78

Refer to Renesas Flash Sample Program Type01 Application Note (R20AN0652) "Example of Creating a Sample Project" to create a project.

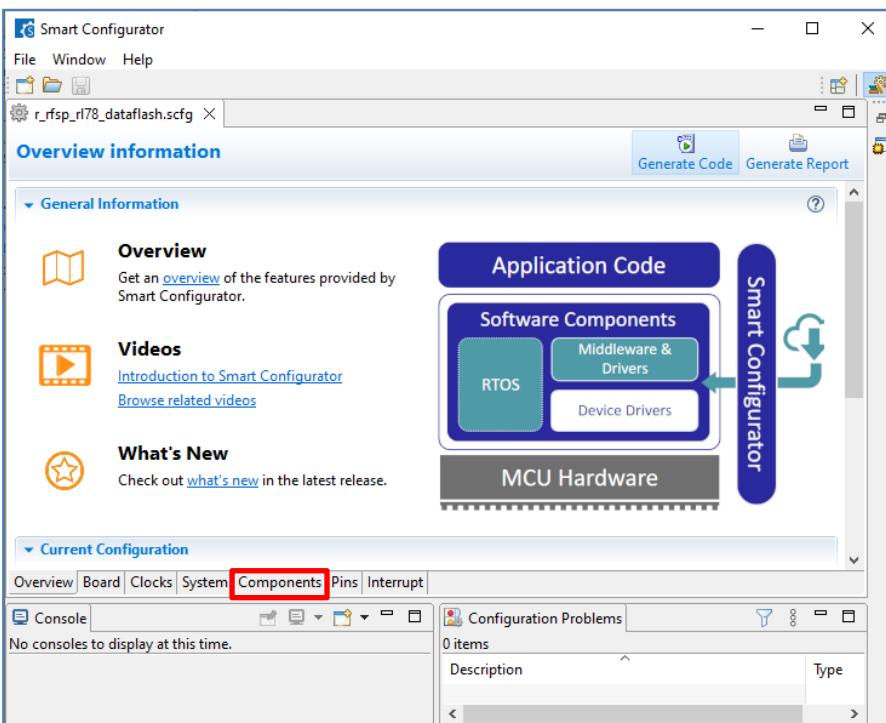
2.2 Example of Source Code Registration

2.2.1 In Case of CS+

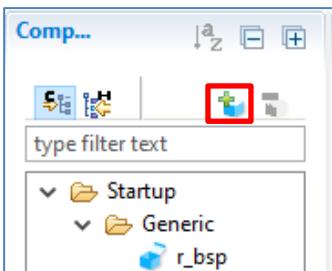
(1) Double-click "Smart Configurator" (design Tool) of "Project Tree", and start Smart Configurator.



(2) Select a "Components" tab.

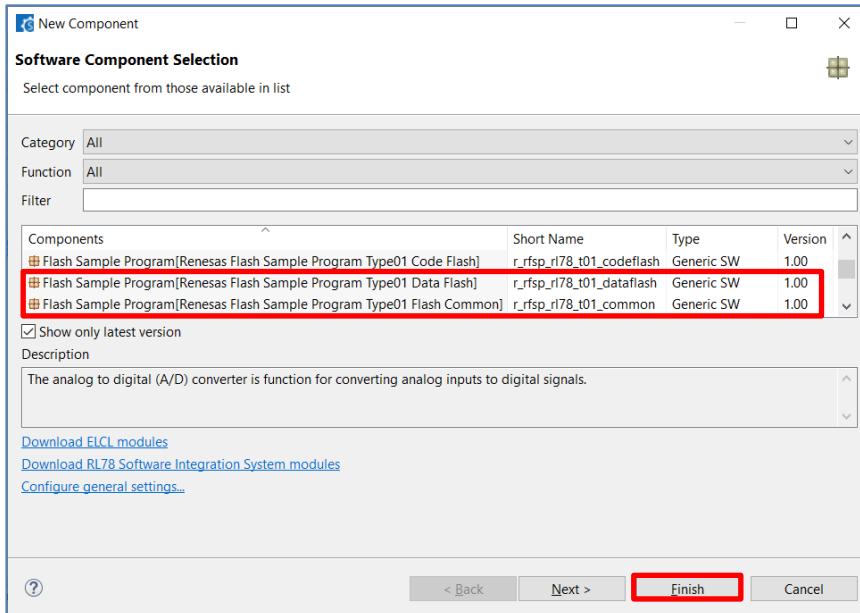


(3) Push the "addition" button of "Components" and open the "addition" dialog of "Components".

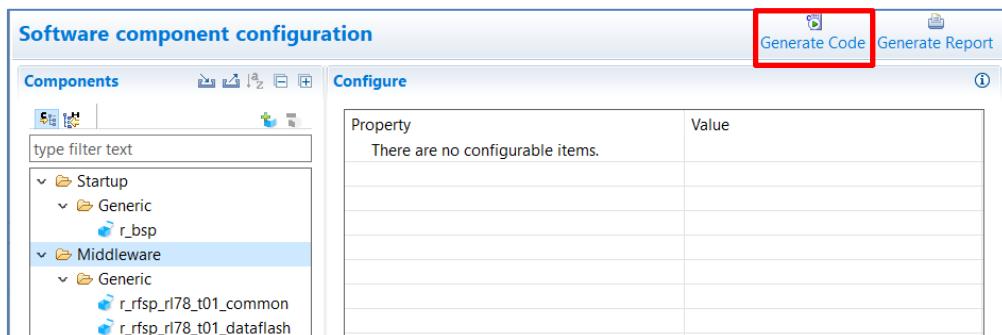


(4) Select the following components and push a "Finish" button.

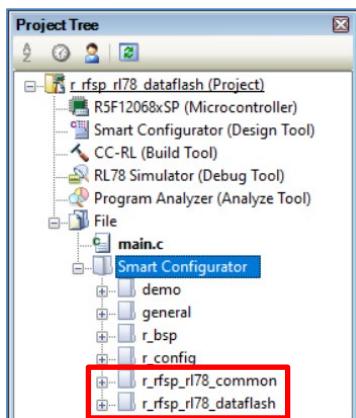
- Flash Sample Program[Renesas Flash Sample Program Type01 Data Flash]
(r_rfsp_rl78_t01_dataflash)
- Flash Sample Program[Renesas Flash Sample Program Type01 Flash Common]
(r_rfsp_rl78_t01_common)



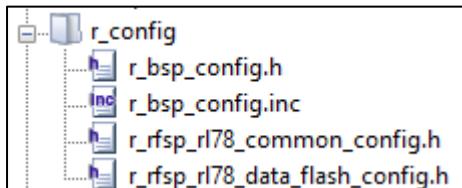
(5) Push a "Generate Code" button and close "Smart Configurator" after the completion of generation for the code.



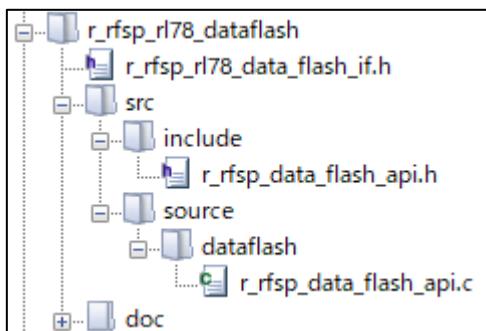
(6) The "r_rfsp_rl78_common" folder and the "r_rfsp_rl78_dataflash" folder is added to the project tree.



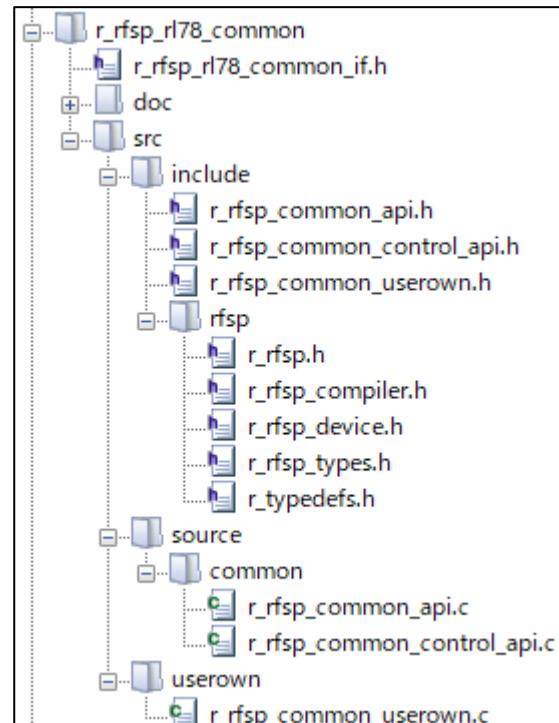
Each folder is developed as follows



The developed r_config folder



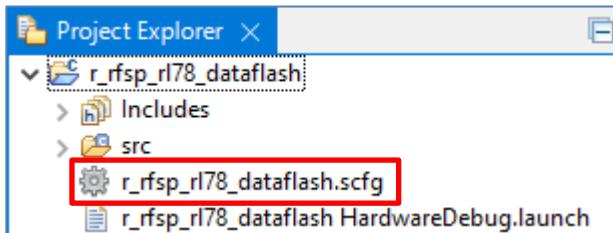
The developed r_rfsp_rl78_dataflash folder



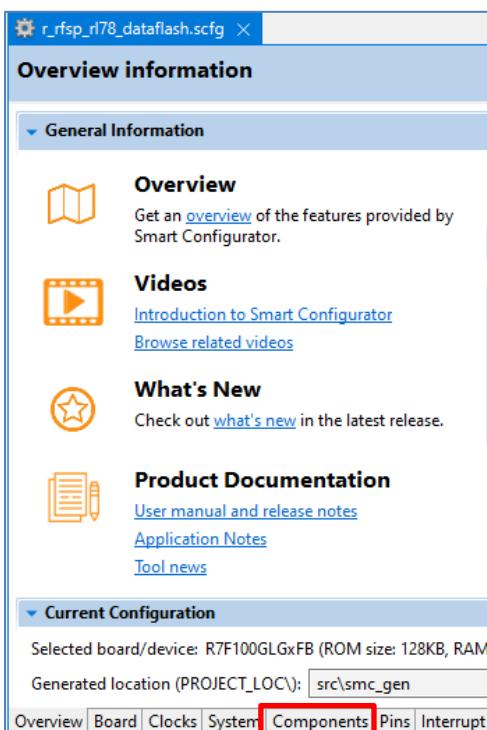
The developed r_rfsp_rl78_common folder

2.2.2 In Case of e²studio

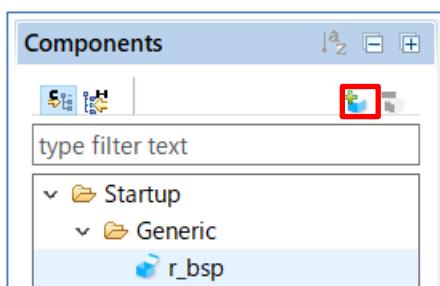
(1) Open the project file of "Smart Configurator" after starting e²studio.



(2) Select a "Components" tab.

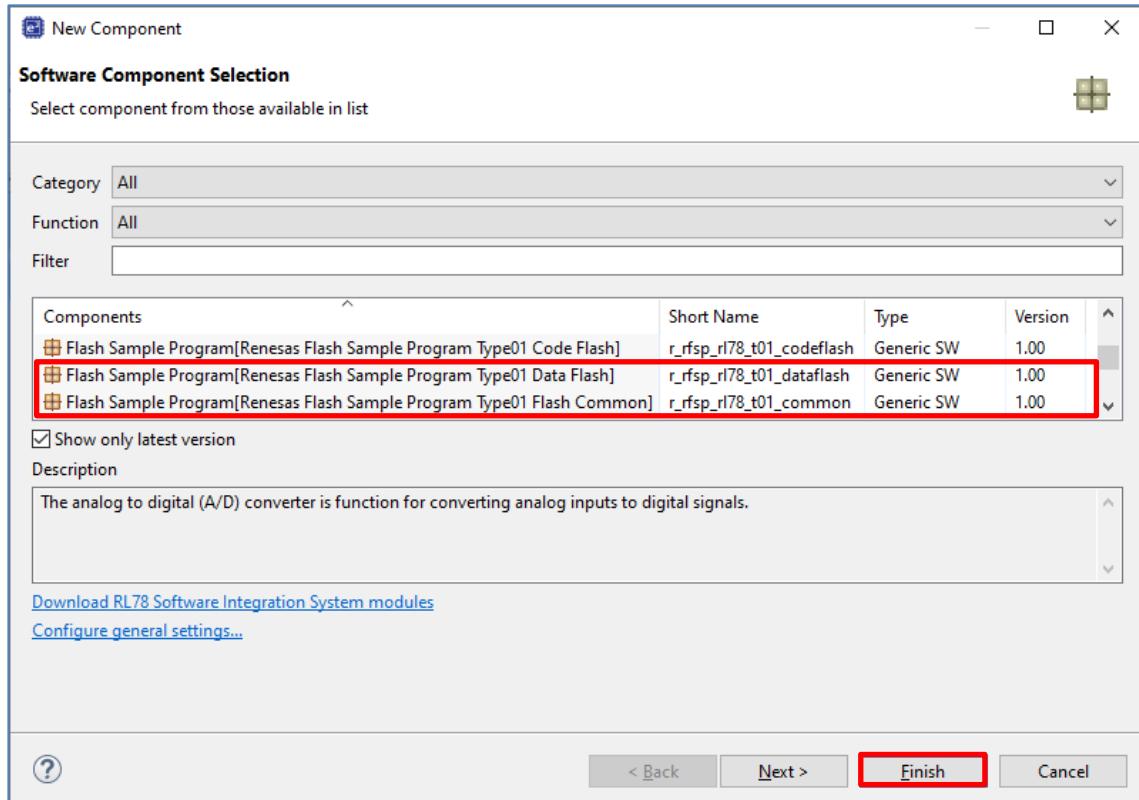


(3) Push the "addition" button of "Components" and open the "addition" dialog of "Components".

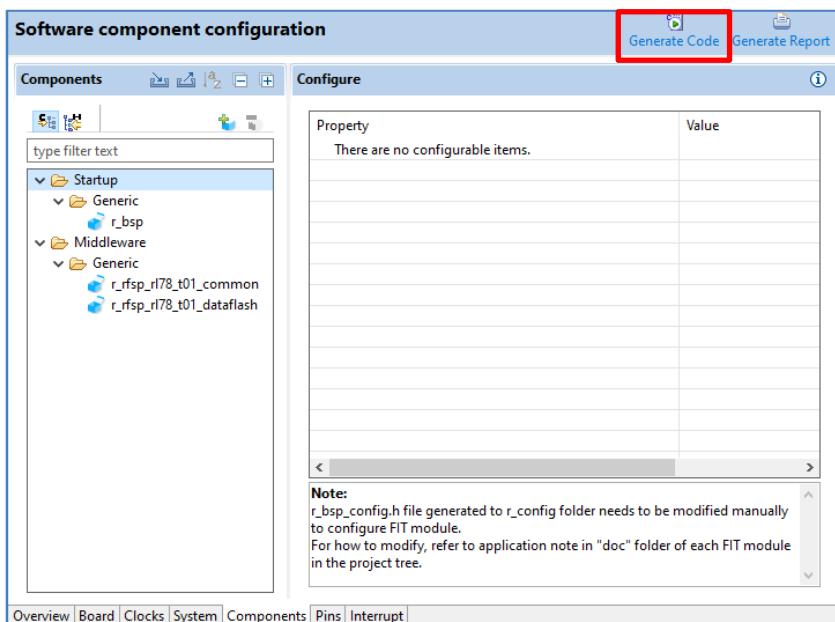


(4) Select the following components and push a "Finish" button.

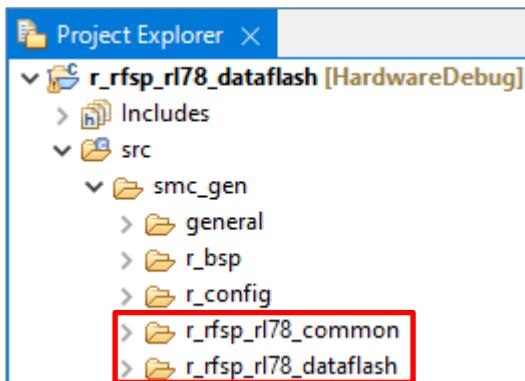
- Flash Sample Program[Renesas Flash Sample Program Type01 Data Flash]
(r_rfsp_rl78_t01_dataflash)
- Flash Sample Program[Renesas Flash Sample Program Type01 Flash Common]
(r_rfsp_rl78_t01_common)



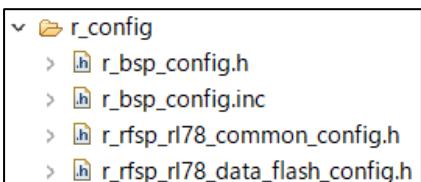
(5) Push a "Generate Code" button and generate the code.



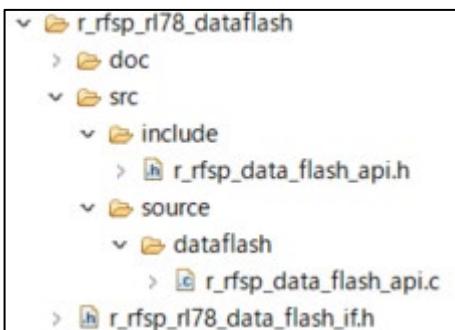
(6) The "r_rfsp_rl78_common" folder and the "r_rfsp_rl78_dataflash" folder is added to the project tree.



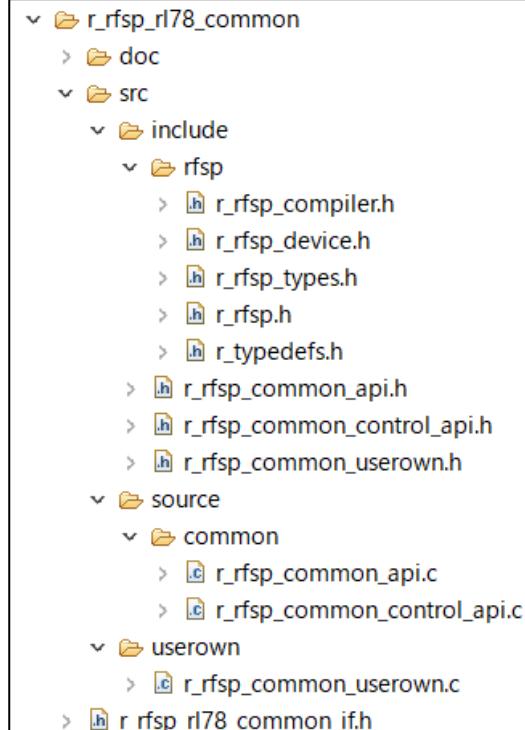
Each folder is developed as follows.



The developed r_config folder



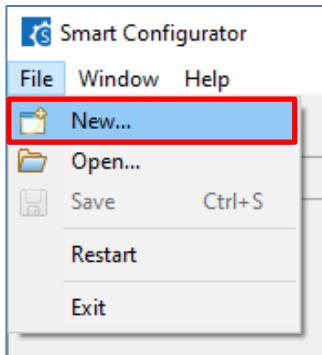
The developed r_rfsp_rl78_dataflash folder



The developed r_rfsp_rl78_common folder

2.2.3 In Case of IAR EW for Renesas RL78

(1) Select "File" [New...] after starting Smart Configurator for RL78.



(2) Select the item of "Platform" and "Toolchain".

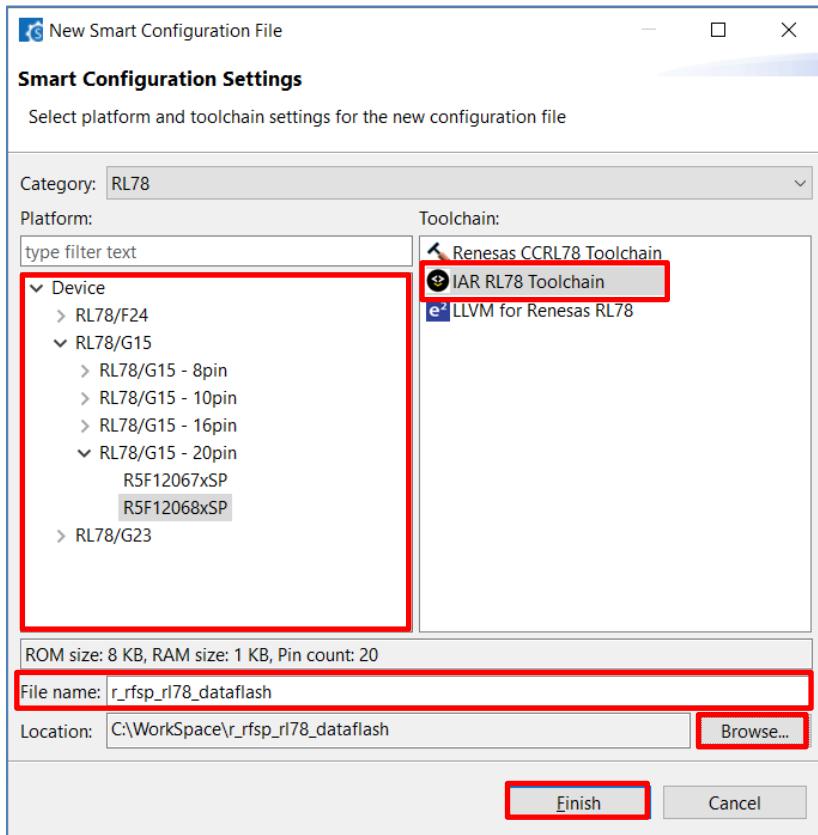
Select the same device as the device selected in "the project of IAR EW for Renesas RL78" by "Platform"...

Select "IAR RL78 Toolchain" as "Toolchain".

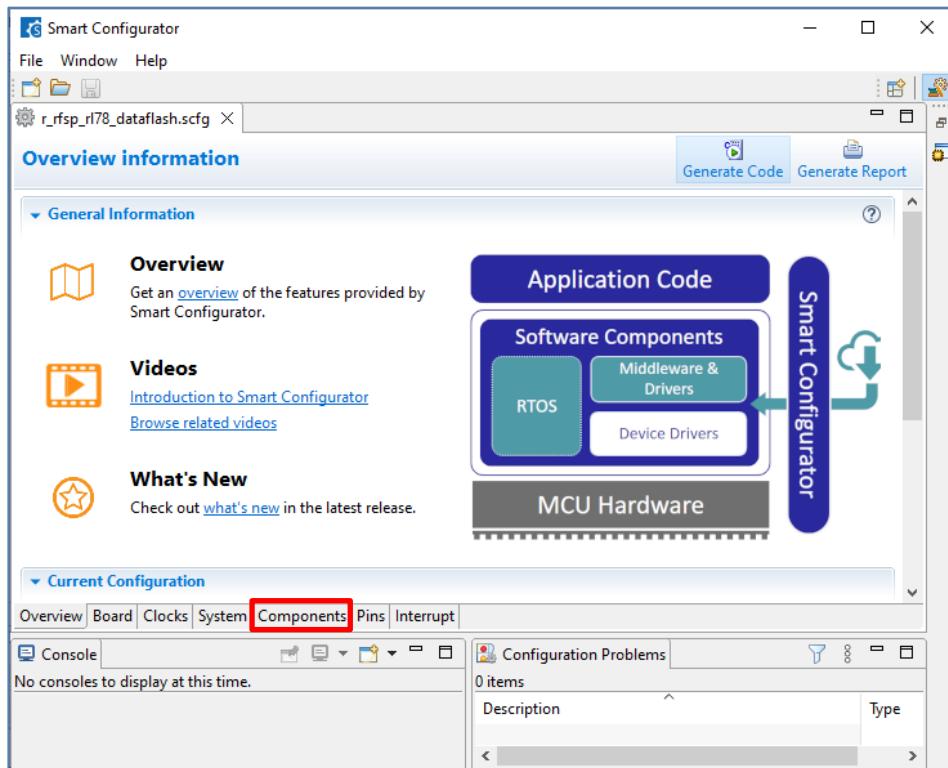
Input arbitrary names into "File name".

Push the "Browse..." button and set the location of the project folder for IAR EW for Renesas RL78. And push "Finish" button.

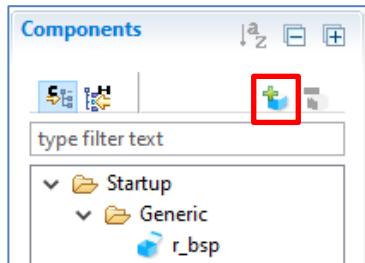
The ".setting" folder and the "<file name>.scfg" file are created to the set location.



(3) Select a "Components" tab.

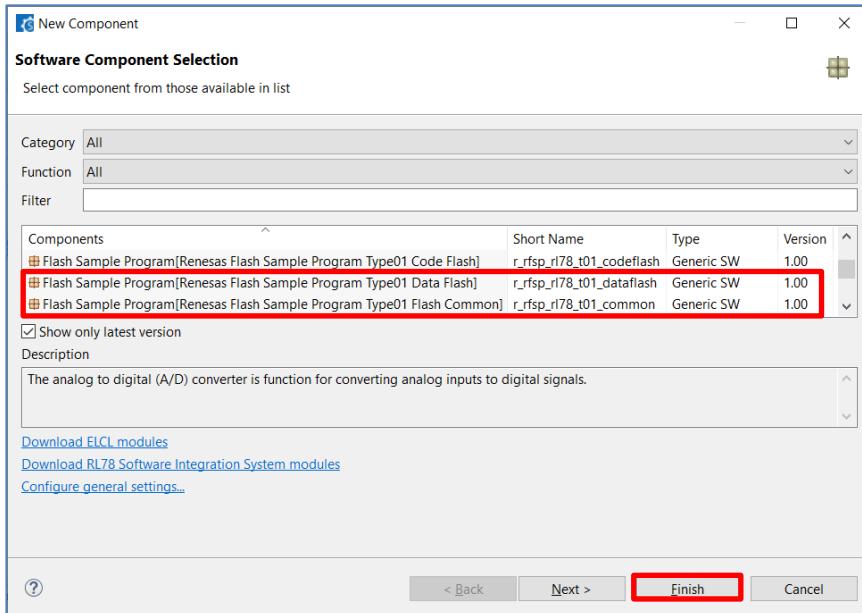


(4) Push the "addition" button of "Components" and open the "addition" dialog of "Components".

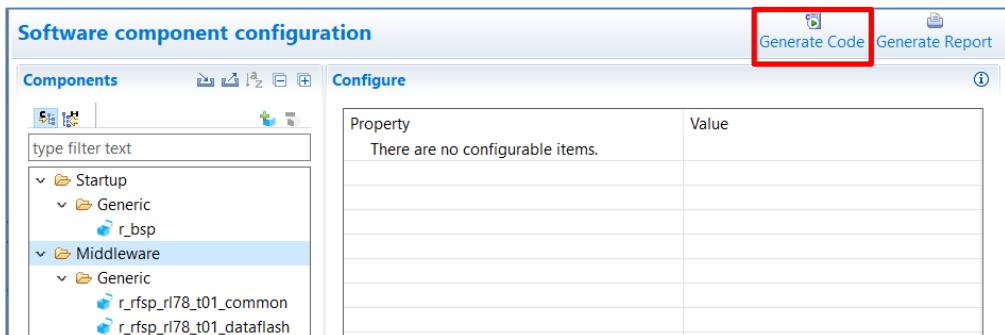


(5) Select the following components and push a "Finish" button.

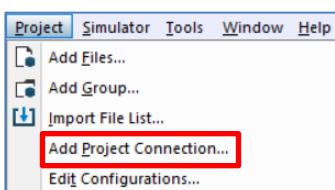
- Flash Sample Program[Renesas Flash Sample Program Type01 Data Flash]
(r_rfsp_rl78_t01_dataflash)
- Flash Sample Program[Renesas Flash Sample Program Type01 Flash Common]
(r_rfsp_rl78_t01_common)



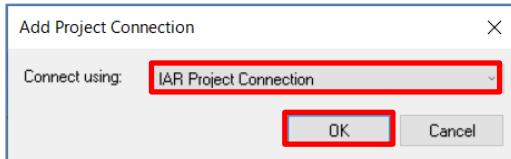
(6) Push a "Generate Code" button and close "Smart Configurator" after the completion of generation for the code.



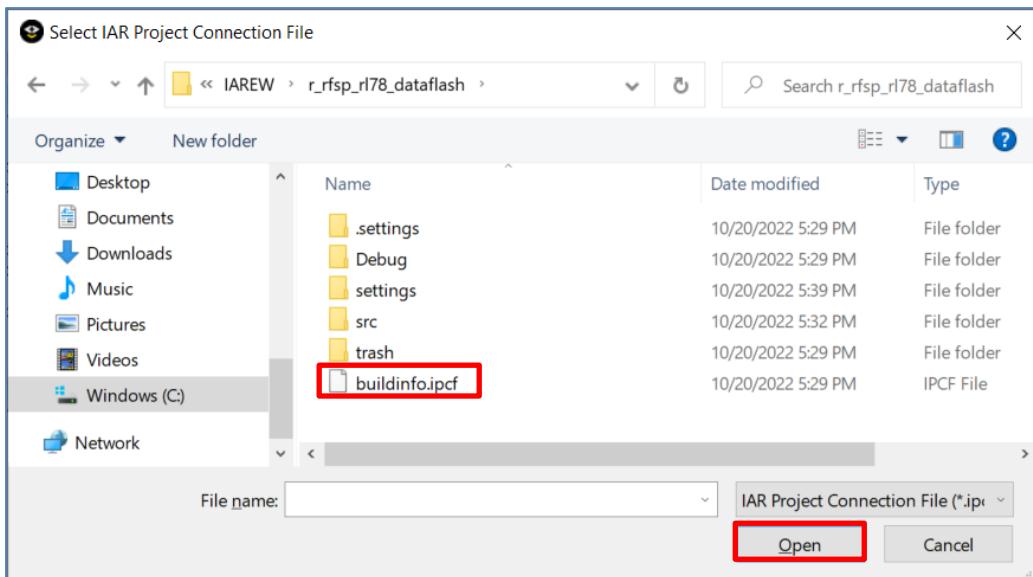
(7) Start IAR EW for Renesas RL78. And select "Project" menu [Add Project Connection], and open the additional dialog of Project Connection.



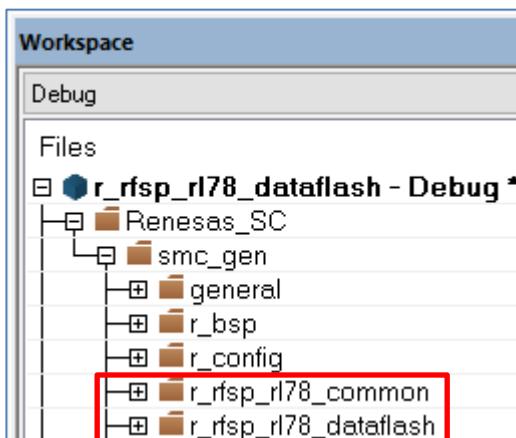
(8)Select “IAR Project Connection”, and push an “OK” button.



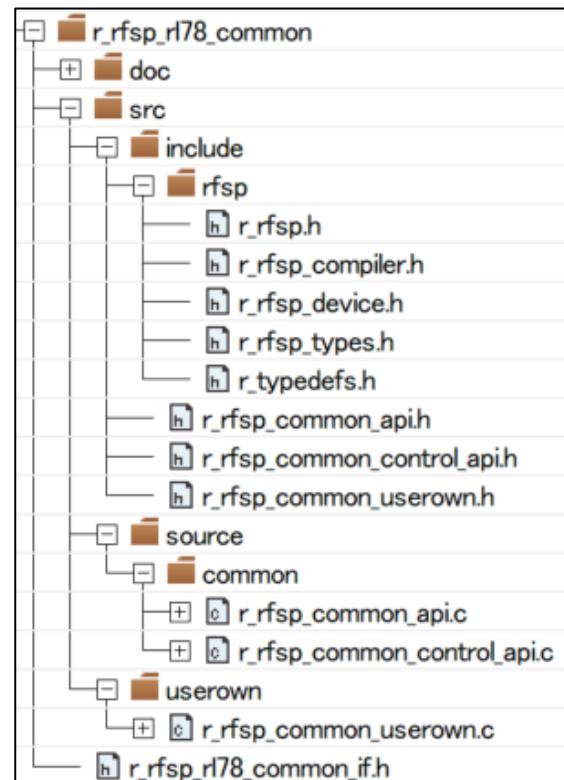
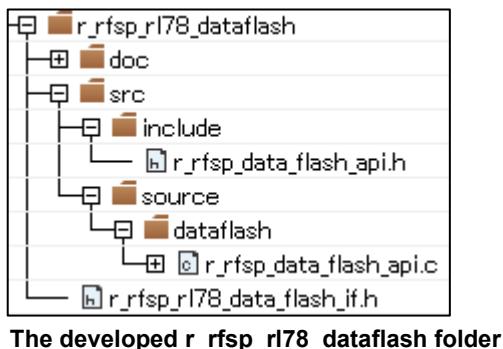
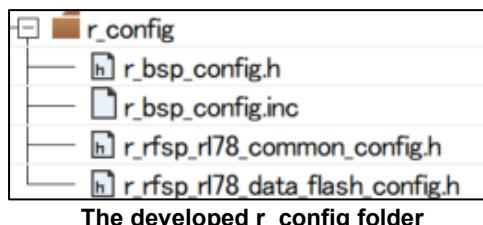
(9) Select the ipcfc file created by Smart Configurator and push an "Open" button.



(10) "r_rfsp_rl78_common" and "r_rfsp_rl78_dataflash" are added to Workspace.



Each folder is developed as follows.



2.3 Project Registration of Sample Program

(1) Extract "DF_sample.zip."

A common file duplicates in the case used at the same time with the sample program for a code flash. In order to prevent duplication, I set and extract the same folder name and the same files are made to be overwritten.

(2) Register the folder of the sample program into the project of CS+, e²studio, or IAR.

* In the case of CS+ or e²studio, because vecttbl.c is not used, it does not need to register it.

(3) Setting the section items

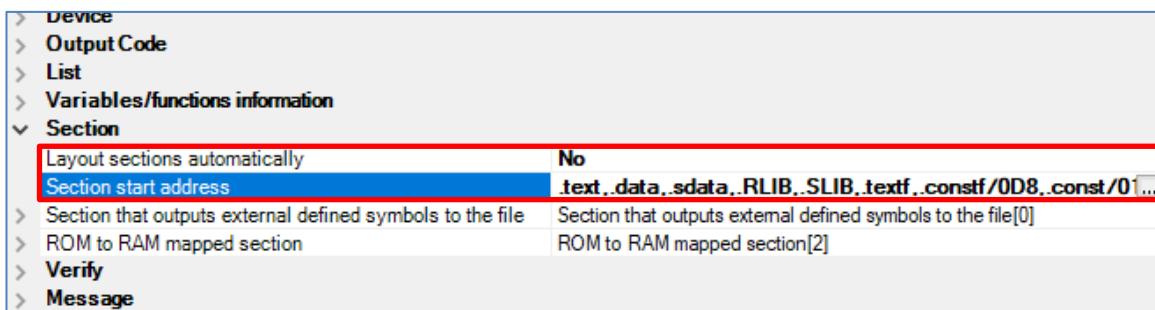
(3-1) Setting of the section items on CS+

Setting of the section Items on CS+ inputs in the "Link Options" tab. (Common in each area)

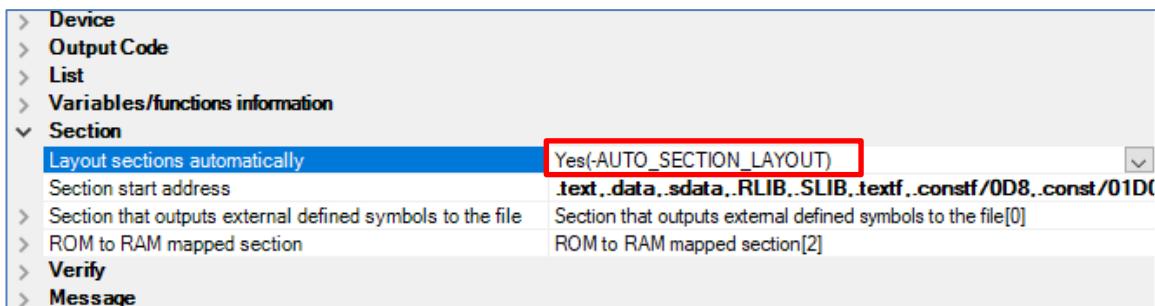
- Setting the [Section] items

Set "No" to [Layout sections automatically], and the section items display on [Section start address]. And setting the following section items.

".text,.data,.sdata,.RLIB,.SLIB,.textf,.constf/0D8,.const/01D00,.dataR,.bss/0FFB00,.sdataR,.sbss/0FFE20"



After set section items, return [Layout sections automatically] to "Yes".

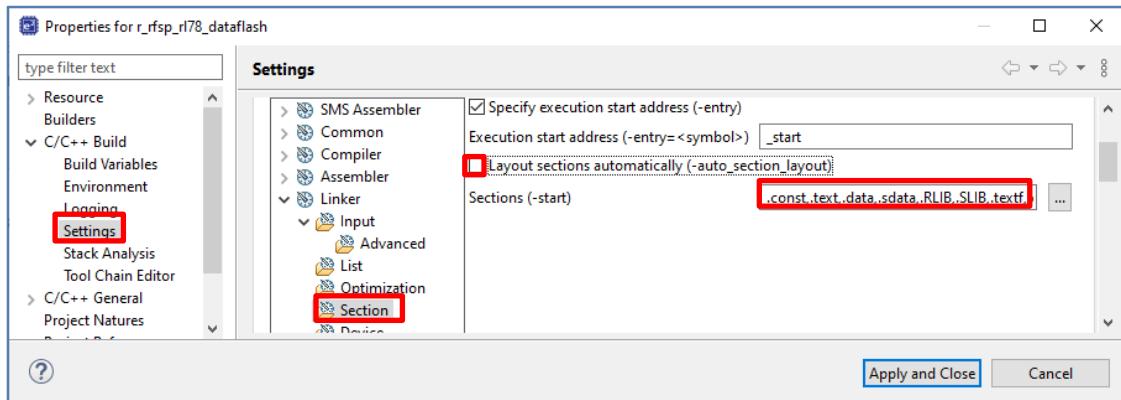


(3-2) Setting of the section items on e²studio

Setting of the section Items on e²studio inputs in the “Properties” window.

Select the [Property] in a project, and open a Properties window. Select "C/C++ Build" [Setting] - "Linker" [Section]. And set section items on the displayed screen. Remove a check mark to [Layout sections automatically(-auto_section_layout)]. And rewrite the contents of the text box of the [Section (-start)] to following section items.

".text,.data,.sdata,.RLIB,.SLIB,.textf,.constf/0D8,.const/01D00,.dataR,.bss/0FFB00,.sdataR,.sbss/0FFE20"

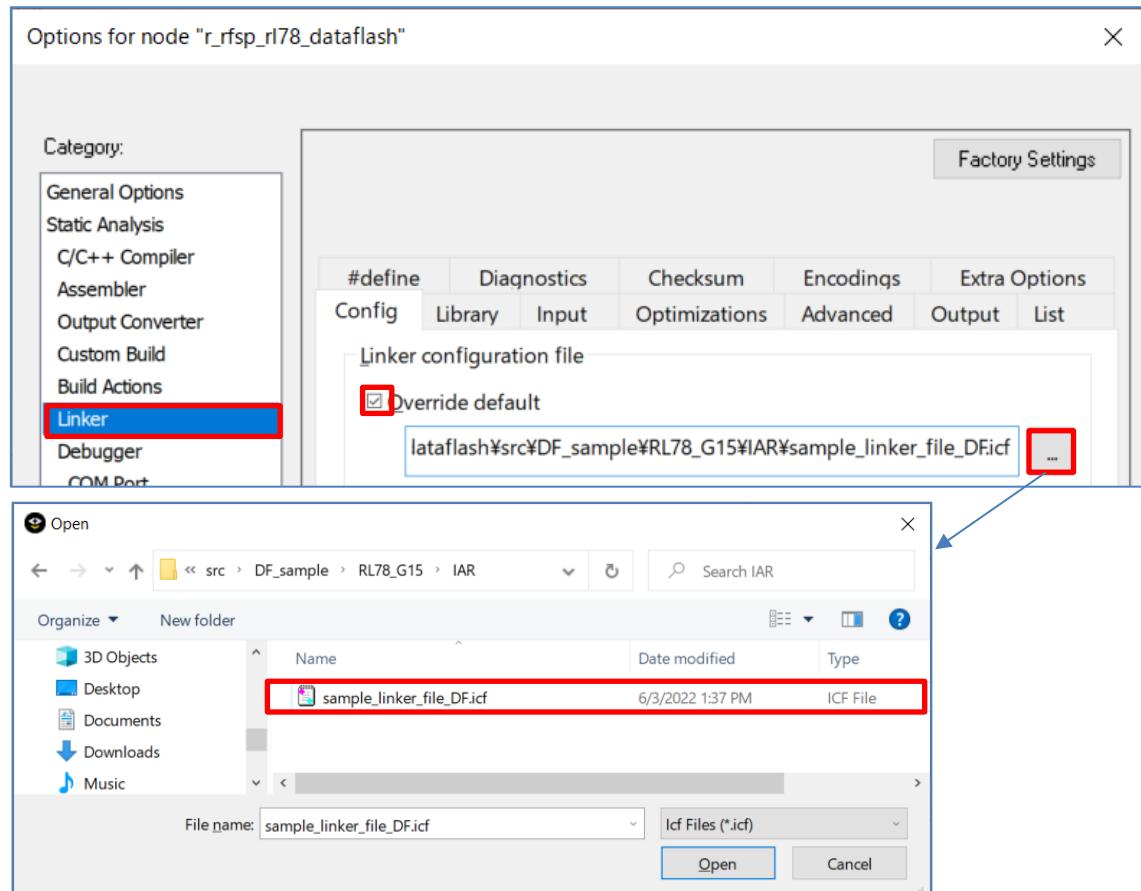


(3-3) Setting of the section items on IAR EW for Renesas RL78

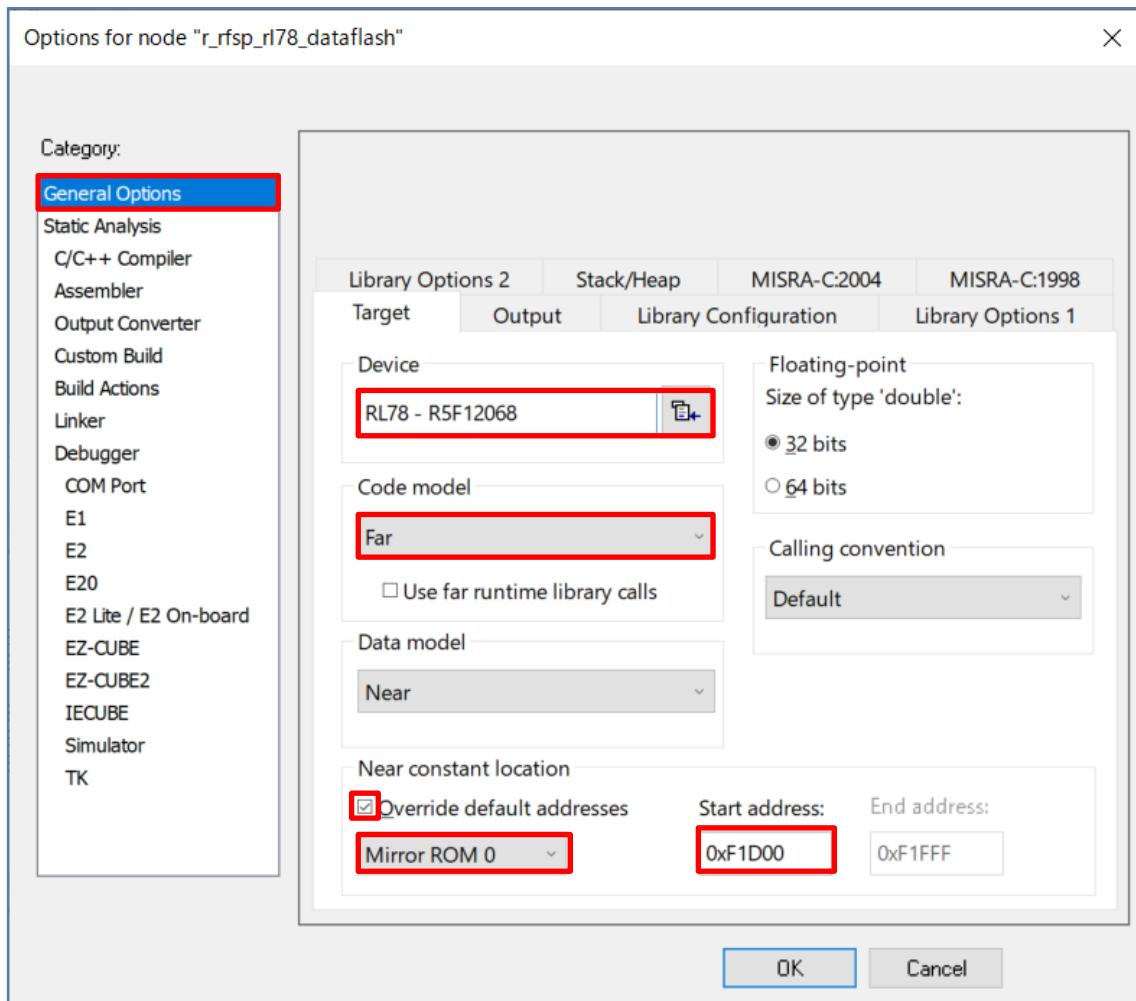
On IAR Embedded Workbench, Linker configuration file (*.icf) describes link setting executed by building. Select "Options" by the click right mouse button of project with tree. Select [Linker] by "Category" in the displayed window, And put a check mark to "Override default" of the [Config] tab. Select Linker configuration file (*.icf) in the "Open" window of "..." button. Select the "sample_linker_file_DF.icf" file prepared for RFSP Type 01.

The "sample_linker_file_DF.icf" file is stored in the folder shown below.

¥DF_sample¥RL78_G15¥IAR¥



Set the items of [General Options] - [Target] tab in the "Options" screen. Select the target device for [Device] and "Far" for [Code model]. To specify the allocation address of the [Near constant location], set the check mark to [Default Address Override (O)], select "Mirror ROM0", and change [Start address:] to 0xF1D00.



(4) Include Path Settings

(4-1) Setting of the include path on CS+

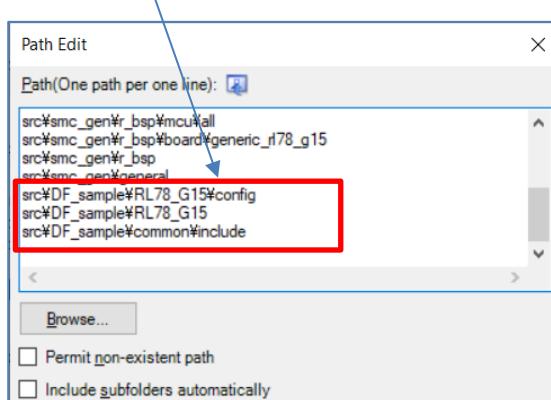
Setting of the include path on CS+ inputs path in "Common Options" tab.

- Add the Include directory path in the "Path Edit" window displayed by selection of [Frequently Used Options(for Compile)] - [Additional include paths].

In the phase where code generation was performed by (5) of "2.2.1 In Case of CS+", the include path of files other than the sample program is registered. For a reason, it needs to register the include path of the sample program.

Those include path to add is shown below.

```
src\DF_sample\common\include
src\DF_sample\RL78_G15
src\DF_sample\RL78_G15\config
```



* It is an example of the include path in the case which extracted DF_sample.zip directly under the src folder.

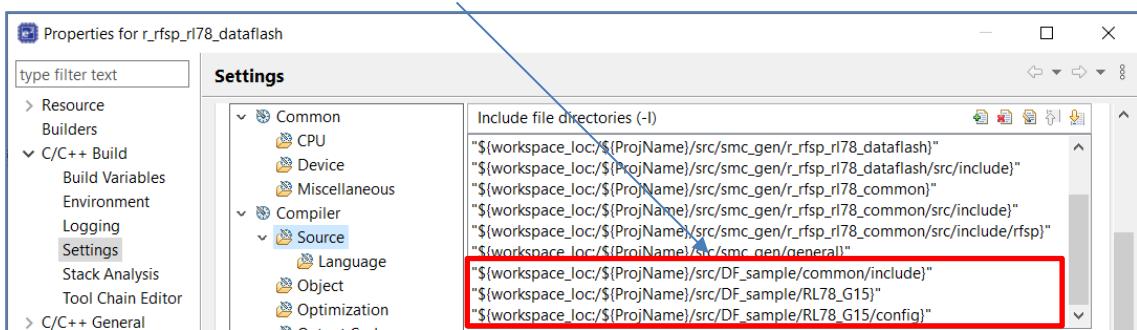
(4-2) Setting of the include path on e²studio

Setting of the include path on e²studio inputs path in “Properties” window.

- Input the Include directory path in the window displayed by selection of "C/C++" build [Setting] - "Compiler" [Source].

Those include path to add is shown below.

```
 ${workspace_loc:${ProjName}/src/DF_sample/common/include}  
 ${workspace_loc:${ProjName}/src/DF_sample/RL78_G15}  
 ${workspace_loc:${ProjName}/src/DF_sample/RL78_G15/config}
```



* It is an example of the include path in the case which extracted DF_sample.zip directly under the src folder.

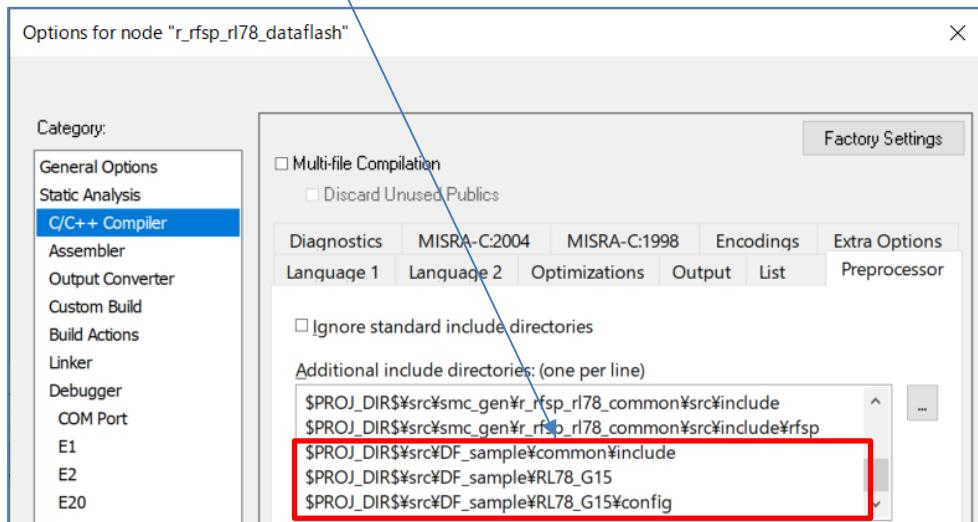
(4-3) Setting of the include path on IAR EW for Renesas RL78

Setting of the include path on IAR Embedded Workbench selects "C/C++ Compiler" of "Category", and inputs path in "Preprocessor" tab.

- Input the Include directory path in the "Edit include Directories" window displayed by selection of [Additional include directories: (one per line)].

Those include path to add is shown below.

```
$PROJ_DIR$src$DF_sample$common$include
$PROJ_DIR$src$DF_sample$RL78_G15
$PROJ_DIR$src$DF_sample$RL78_G15$config
```



* It is an example of the include path in the case which extracted DF_sample.zip directly under the src folder.

(5) Device Item Settings

(5-1) Setting of the device Items on CS+

Refer to the chapter of "Device Item Settings" of Renesas Flash Sample Program Type01 Application Note (R20AN0652) .

(5-2) Setting of the device Items on e²studio

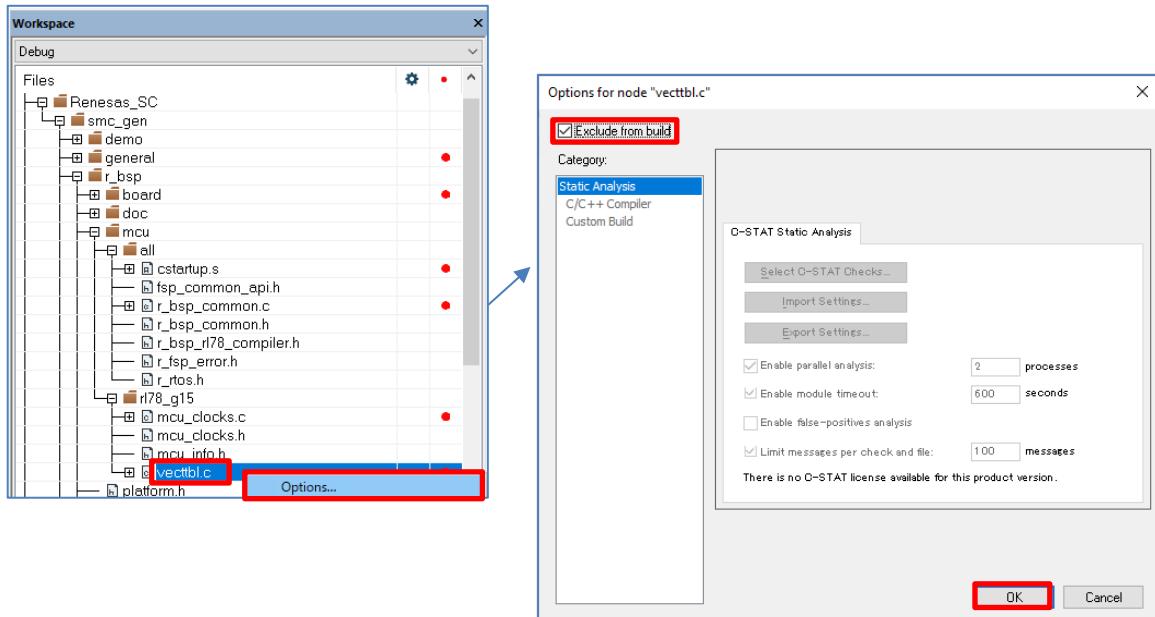
Refer to the chapter of "Device Item Settings" of Renesas Flash Sample Program Type01 Application Note (R20AN0652) .

(5-3) Setting of the device Items on IAR EW for Renesas RL78

Build including vecttbl.c prepared as a sample program. A user option byte's value is set to 0xEEFF9, and an on-chip debugging option byte's value is set to 0x85.

When the code is generated by Smart Configurator, vecttbl.c is generated to a "smc_gen¥r_bsp¥mcu¥rl78_g15¥" folder. And because vecttbl.c duplicates, it is necessary to repeat this file.

Right-click a mouse by "Renesas_SC¥smc_gen¥r_bsp¥mcu¥rl78_g15¥vecttbl.c" in the [project] on a tree. And select an "option" and set a "check" to [Exclude from build] in the displayed screen.



(6) Execute the sample program from a main function.

Describe the sample_dataflash_main function included in r_flash_sample_dataflash_rl78g1x.c like the "main function" for the project. And build, download and execute it.

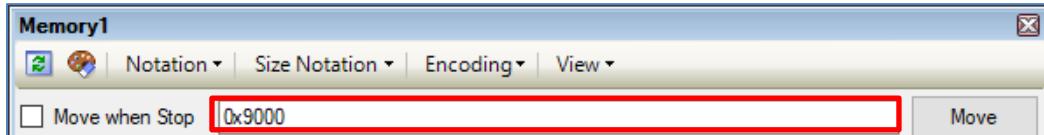
- * The header file which described the prototype declaration for sample_dataflash_main function.
Include prepared "r_flash_sample_dataflash_rl78g1x.h."

2.4 The Check of Operation for Sample Program

The block 0(0x9000) of a data flash area is erased. And 64 bytes of data is programmed from the top of the block 0. Confirm this operation by the following methods.h

2.4.1 In Case of CS+

- (1) Select [Debug]menu - [Download] and start debugging.
- (2) After selecting [View]menu - [Memory], select "Memory1", "Memory2", "Memory3", or "Memory4", and display a memory window.
- (3) Set "0x9000" to the address of a memory window, and display the block 0 of a data flash area.



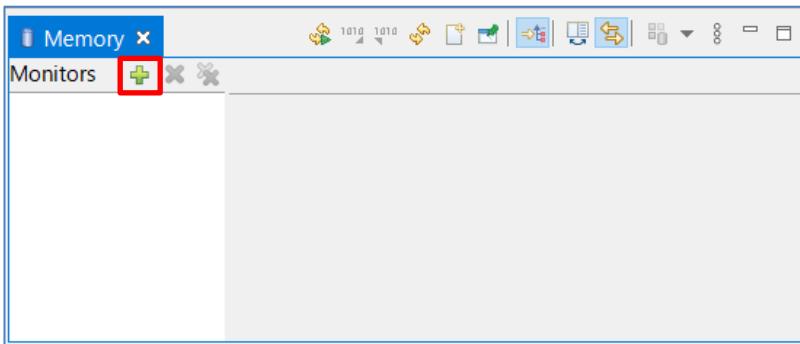
- (4) Select [Debug]menu - [Go] and the program is executed. Check that the value of "0x9000-0x903F" displayed on the memory window has changed after stopping the program.

The screenshot shows the 'Memory1' window displaying memory data from address 0x9000 to 0x903F. The data is organized into a grid:

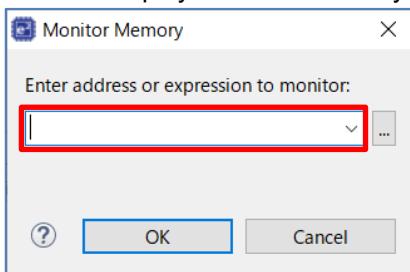
	+0	+1	+2	+3	+4	+5	+6	+7	+8	+9	+a	+b	+c	+d	+e	+f	ASCII
09000	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
09010	10	11	12	13	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F
09020	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	!"#\$%&'()*+,-./
09030	30	31	32	33	34	35	36	37	38	39	3A	3B	3C	3D	3E	3F	0123456789:;<=>?
09040	FF	?????????????????															

2.4.2 In Case of e²studio

- (1) Select [Run]menu - [Debug] and start debugging.
- (2) Select [Window]menu - [Show View] - [Memory] and display Memory view.
- (3) Push " + " button and display the Monitor Memory window.



- (4) Input "0x9000" into the address to monitor, and push the OK button. The block 0 of a code flash area is displayed on the memory view.



- (5) After the program is executed, check that the value of "0x9000-0x903F" displayed on the memory window is changing.

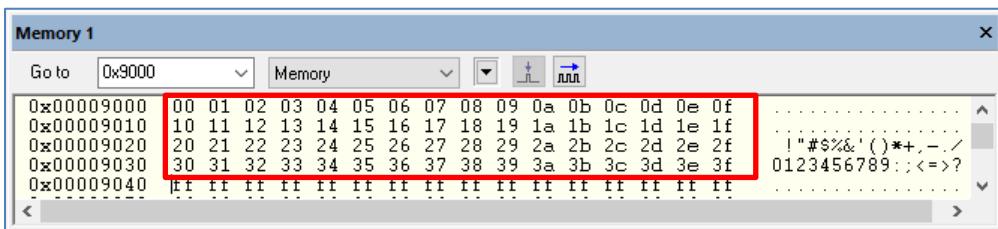
Address	0 - 3	4 - 7	8 - B	C - F
00000000000009000	03020100	07060504	0B0A0908	0F0E0D0C
00000000000009010	13121110	171F1514	1B1A1918	1F1E1D1C
00000000000009020	23222120	27200x9004	2B2A2928	2F2E2D2C
00000000000009030	33323130	37363534	3B3A3938	3F3E3D3C
00000000000009040	FFFFFFF	FFFFFFF	FFFFFFF	FFFFFFF

2.4.3 In Case of IAR EW for Renesas RL78

- (1) Select [Project] menu - [Download and Debug] and start debugging.
- (2) After select [View]menu - [Memory], select either from "Memory 1" to "Memory 4", and the memory window is displayed.
- (3) Set "0x9000" to the address of the memory window. And the block 0 of code flash area is displayed.



- (4) After the program is executed, check that the value of "0x9000-0x903F" displayed on the memory window is changing.



3. Precautions for Specifications

(1) Allocation of the user program for flash memory reprogramming operation

Allocate the user program for programming the code/data flash area to the code flash area. Self-programming by fetching from the RAM is prohibited. Additionally, reprogramming the boot area and the block for storing the user program for executing self-programming is prohibited.

(2) Prohibit the interrupts in self-programming mode

Prohibit an interrupt before setting the self-programming mode. To prohibit an interrupt, clear (0) the IE flag by the DI instruction in the same way as in the normal operation mode.

(3) Setting the CPU operating frequency for the flash memory sequencer

When using the flash memory sequencer to reprogram the code/data flash memory, set the value corresponding to the CPU operating frequency in the FSET4-0 bits of the FSSET register before proceeding. Note that if reprogramming is attempted while the value corresponding to the CPU operating frequency is not correct, operation is undefined and written data are not guaranteed. Even if the values in the flash memory are as expected immediately after reprogramming, retaining the values for any specified period is not guaranteed.

(4) Operation setting of high-speed on-chip oscillator

The high-speed on-chip oscillator should be kept operating before executing self-programming. If it is stopped, it should be made to operate again (HIOSTOP = 0), and the flash self-programming code should be re-executed after 30 us have elapsed.

(5) Restriction of execution of other operations during self-programming

Do not execute other settings or instructions which are not related to the self-programming procedure during the self-programming execution flow.

(6) User program operation during flash memory reprogramming operation

The CPU is stopped during reprogramming through self-programming. The code flash or data flash memory cannot be accessed while it is being reprogrammed.

4. Reference Document

Please get the latest version of each document from the Renesas Electronics Corp. website (<https://www.renesas.com>).

No	Document Title	Document Number
1	RL78/G15 User's Manual Hardware	R01UH0959
2	RL78 Family Board Support Package Module	R01AN5522
3	Renesas Flash Sample Program Type01 Application Note	R20AN0652
4	E1/E20/E2 Emulator, E2 Emulator Lite Additional Document for User's Manual (Notes on Connection of RL78)	R20UT1994

5. Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Oct.31.22	—	Newly created.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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